



DN0150ALP4 / DN0150BLP4

50V NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ultra Low Profile (0.4mm max)
- Complementary PNP Type Available (DP0150ALP4/DP0150BLP4)
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free, "Green" Device (Note 2)
- Qualified to AEC-Q101Standards for High Reliability

Mechanical Data

- Case: DFN1006H4-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0008 grams (approximate)

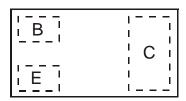
DFN1006H4-3







Device Symbol



Top View Pin Configuration

Ordering Information (Note 3)

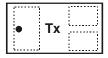
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DN0150ALP4-7	T3	7	8	3,000
DN0150ALP4-7B	Т3	7	8	10,000
DN0150BLP4-7	T4	7	8	3,000
DN0150BLP4-7B	T4	7	8	10,000

Notes:

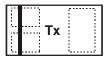
- 1. No purposefully added lead.
- 2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com.

Marking Information

DN0150ALP4-7 DN0150BLP4-7



Top View Dot Denotes Collector Side DN0150ALP4-7B DN0150BLP4-7B



Top View Bar Denotes Base and Emitter Side Tx = Product Type Marking Code T5 = DN0150ALP4

T6 = DN0150BLP4



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	50	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current – Continuous	Ic	100	mA
Peak Pulse Collector Current	I _{CM}	200	mA
Base Current	lв	30	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P_{D}	450	mW
Thermal Resistance, Junction to Ambient (Note 4)	$R_{ heta JA}$	278	°C/W
Operating and Storage Temperature Range	T_J,T_STG	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage		V(_{BR)CBO}	60	_	_	V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	e (Note 5)	V(BR)CEO	50	_	_	V	$I_C = 1 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage		V(_{BR)EBO}	5	_	_	V	$I_E = 10 \mu A, I_C = 0$
Collector Cut-Off Current		I _{CBO}	_	_	0.1	μΑ	$V_{CB} = 60V, I_{E} = 0$
Emitter Cut-Off Current		I _{EBO}	_	_	0.1	μΑ	$V_{EB} = 5V, I_{C} = 0$
ON CHARACTERISTICS (Note 5)							
Collector-Emitter Saturation Voltage		V _{CE(SAT)}	_	0.10	0.25	V	$I_C = 100 \text{mA}, I_B = 10 \text{mA}$
DC Current Gain	DN0150ALP4		120	_	240		$V_{CE} = 6V, I_{C} = 2mA$
	DN0150BLP4	h _{FE}	200	_	400		VCE = OV, IC = ZITIA
SMALL SIGNAL CHARACTERISTIC	SMALL SIGNAL CHARACTERISTICS						
Transition Frequency		f⊤	60	_	_	MHz	$V_{CE} = 10V$, $I_E = -1mA$ f = 30MHz
Output Capactiance		C _{ob}	_	1.3	_	pF	$V_{CB} = 10V, I_{E} = 0,$ f = 1MHz

Notes:

- 4. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 5. Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤2%





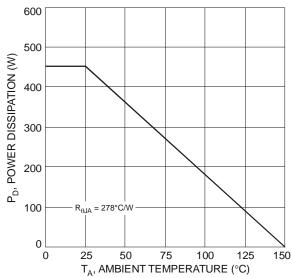
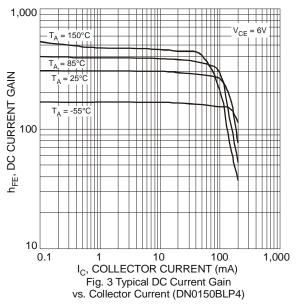
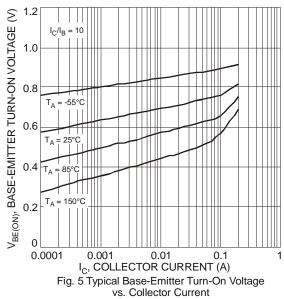
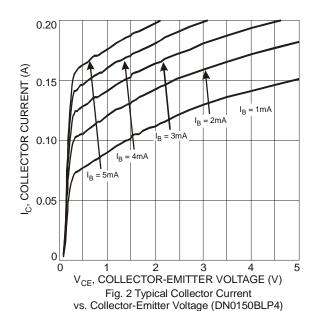
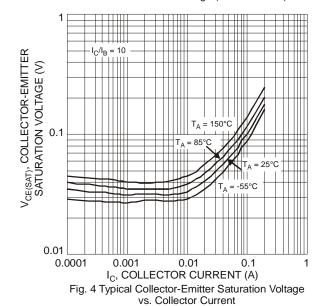


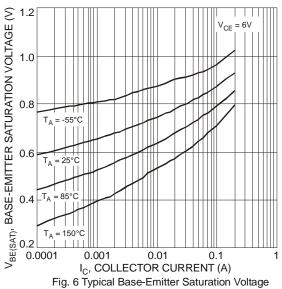
Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)





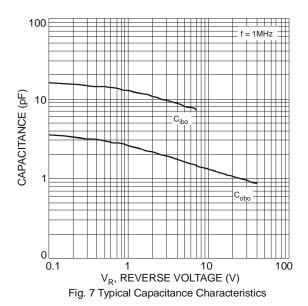


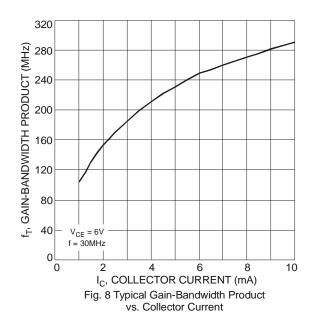




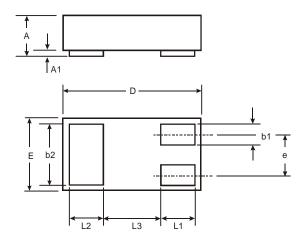






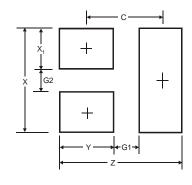


Package Outline Dimensions



DFN1006H4-3					
Dim	Min	Max	Тур		
Α	_	0.40	_		
A1	0	0.05	0.02		
b1	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	_	_	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3		_	0.40		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
Х	0.7
X1	0.25
Υ	0.4
С	0.7



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